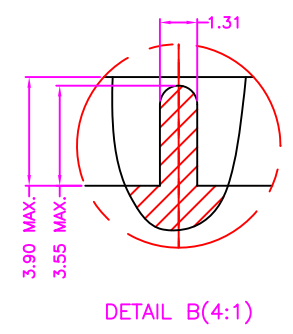
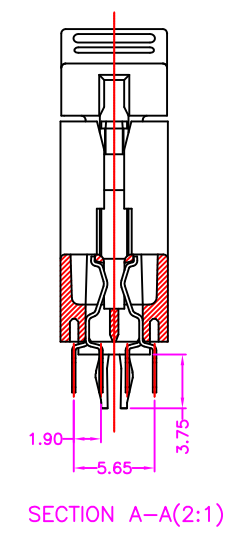
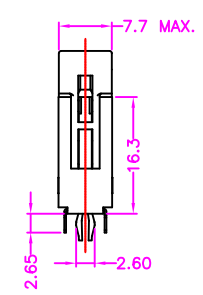
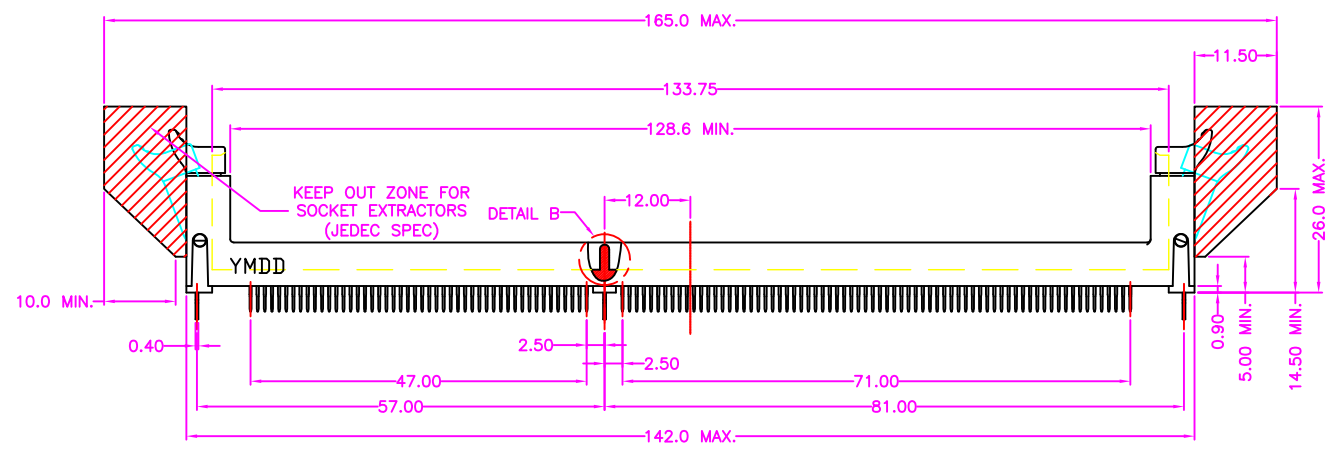


**MATERIALS**  
 HOUSING: THERMOPLASTIC (UL 94V-0)  
 EJECTOR: THERMOPLASTIC (UL 94V-0)  
 BOARDLOCK: COPPER ALLOY, TIN PLATING  
 TERMINAL: COPPER ALLOY, GOLD PLATED ON CONTACT AREA  
 TIN PLATING ON SOLDER TAIL

**SPECIFICATION**  
 CURRENT RATING: 1 AMP MAX  
 DIELECTRIC WITHSTANDING: 500V AC FOR ONE MINUTE  
 CONTACT RESISTANCE: 30m OHMS MAX  
 INSULATION RESISTANCE: 1000M OHMS MIN AT DC 500V  
 OPERATION TEMPERATURE: -55°C~+85°C



**PART NUMBER:**  
**4MSDA - 240 \* T - 111 \***

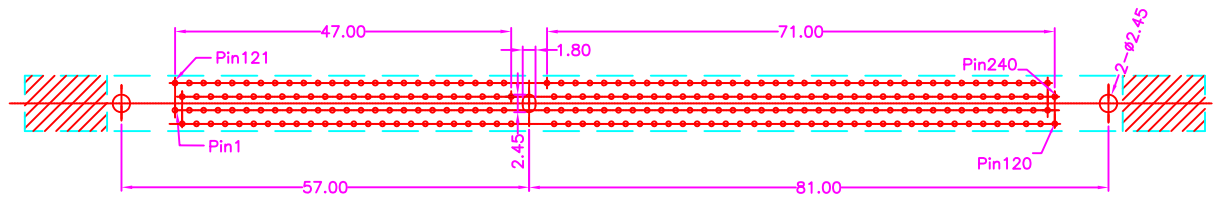
SERIES ————  
 NO. OF POS. ————  
 CONTACT PLATED OPTION ————  
 1: GOLD FLASH  
 3: 3u" GOLD  
 5: 5u" GOLD  
 6: 10u" GOLD  
 7: 15u" GOLD  
 9: 30u" GOLD

HOUSING COLOR OPTION  
 BLANK: BLACK  
 BL: BLUE

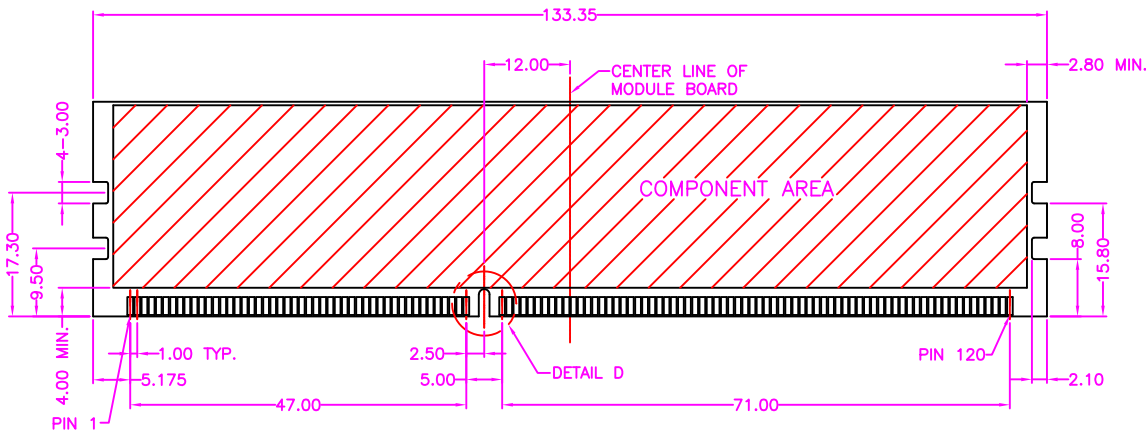
TRAY PACKAGE ————  
 TIN PLATING ON SOLDER TAIL ————

<b>Cyberconn Technology Co., Ltd.</b> www.cyberconn.com.tw Tel:+886-3-4951314						
TOLERANCES		MEMORY SOCKET SERIES				
X.X ±0.3		TITLE DDR III DIMM SOCKET 240 PIN, 1.00mm PITCH, PCB MOUNT VERTICAL, FEMALE, WITH BOARDLOCK, H=26.6mm				
X.XX ±0.2		DRAWN BY		CHECKED BY		APPROVED BY
X.XXX ±0.1		Tina		Lion		Benson
Angle ±5°		UNIT	SCALE	SIZE	DRAW NO.	REV. Sheet
		10033	MM	NONE	A4	4MSDA-001 A 1/2

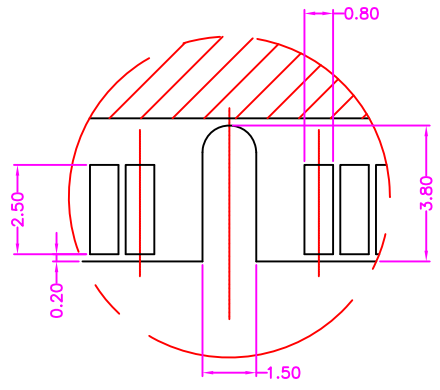
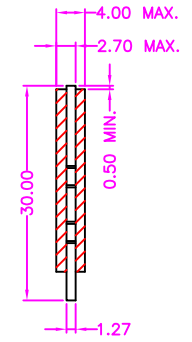
A	RELEASE	2014.10.27
REV.	DESCRIPTION	DATE




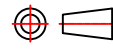
P.C.B LAYOUT  
TOP VIEW ±0.05



RECOMMENDED MODULE CONFIGURATION



DETAIL D(5:1)

 <b>Cyberconn Technology Co., Ltd.</b> www.cyberconn.com.tw Tel:+886-3-4951314						
TOLERANCES		TITLE MEMORY SOCKET SERIES DDR III DIMM SOCKET 240 PIN, 1.00mm PITCH, PCB MOUNT VERTICAL, FEMALE, WITH BOARDLOCK, H=26.6mm				
X.X ±0.3 X.XX ±0.2 X.XXX ±0.1 Angle ±5°		DRAWN BY		CHECKED BY		APPROVED BY
		<i>Tina</i>		<i>Lion</i>		<i>Benson</i>
		UNIT	SCALE	SIZE	DRAW NO.	REV. Sheet
		10033	MM	NONE	A4 4MSDA-001	A 2/2

A	RELEASE	2014.10.27
REV.	DESCRIPTION	DATE